

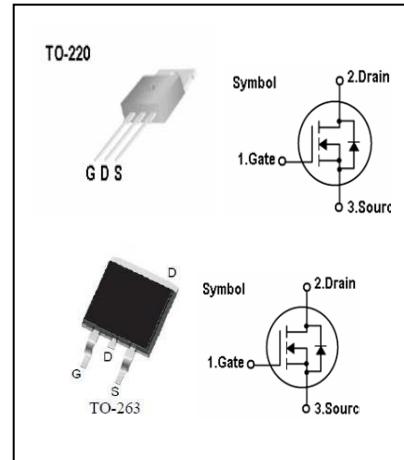
## N-Channel MOSFET

### Features

- 90V,150A,Rds(on)(typ)=4.5mΩ @Vgs=10V
- High Ruggedness
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability
- Split-Gate MOS Technology

### General Description

This Power MOSFET is produced using Si-Tech's advanced Split-Gate MOS Technology. This latest technology has been especially designed to minimize on-state resistance, have a high rugged avalanche characteristics. These devices are well suited for low voltage application such as automotive, DC/DC converters, and high efficiency switch for power management in portable and battery products.



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain-Source Voltage	90	V
I <sub>D</sub>	Continuous Drain Current (T <sub>c</sub> =25°C)	150	A
	Continuous Drain Current (T <sub>c</sub> =100°C)	105	A
I <sub>DM</sub>	Pulsed Drain Current (Note 1)	600	A
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	637	mJ
P <sub>D</sub>	Maximum Power Dissipation (T <sub>c</sub> =25°C)	227	W
	Derating Factor above 25°C	1.26	W/°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +175	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +175	°C

### Thermal Characteristics

Symbol	Parameter	Max.	Units
R <sub>th j-c</sub>	Thermal Resistance, Junction to case	0.66	°C/W
R <sub>th c-s</sub>	Thermal Resistance, Case to Sink	0.5	°C/W
R <sub>th j-a</sub>	Thermal Resistance, Junction to Ambient	62.0	°C/W

***Si-Tech*****SI-TECH SEMICONDUCTOR CO.,LTD****S90N045R/S**

## Electrical Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	90	-	-	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=72\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate Leakage Current, Forward	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
	Gate Leakage Current, Reverse	$V_{\text{GS}}=-20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	-100	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	2	3	4	V
$R_{\text{DS(on)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	4.5	5.5	$\text{m}\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DD}}=40\text{V}$	-	55	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	15	-	nC
$Q_{\text{gd}}$	Gate-Drain Charge		-	13	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=40\text{V}, V_{\text{GS}}=10\text{V}$	-	20.1	-	ns
$t_r$	Turn-on Rise Time		-	38.9	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	45.1	-	ns
$t_f$	Turn-off Fall Time		-	22.8	-	ns
$C_{\text{iss}}$	Input Capacitance -	$V_{\text{DS}}=0\text{V}$	-	3086	-	pF
$C_{\text{oss}}$	Output Capacitance		-	1057	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	26.0	-	pF

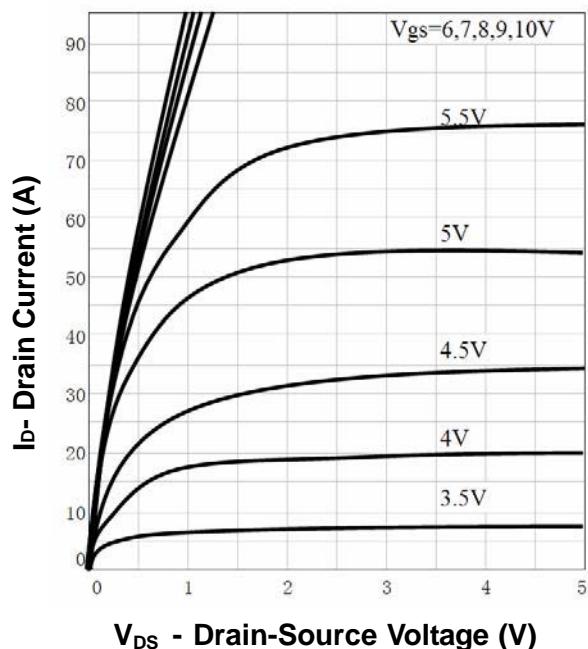
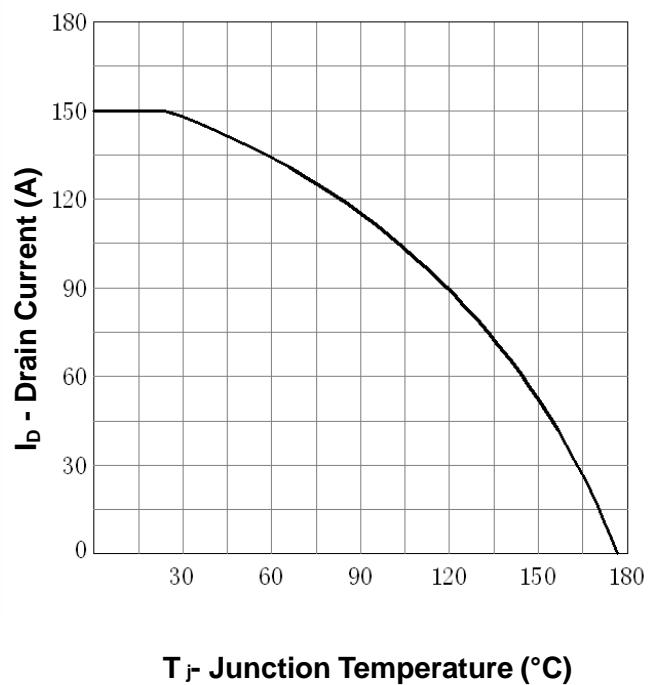
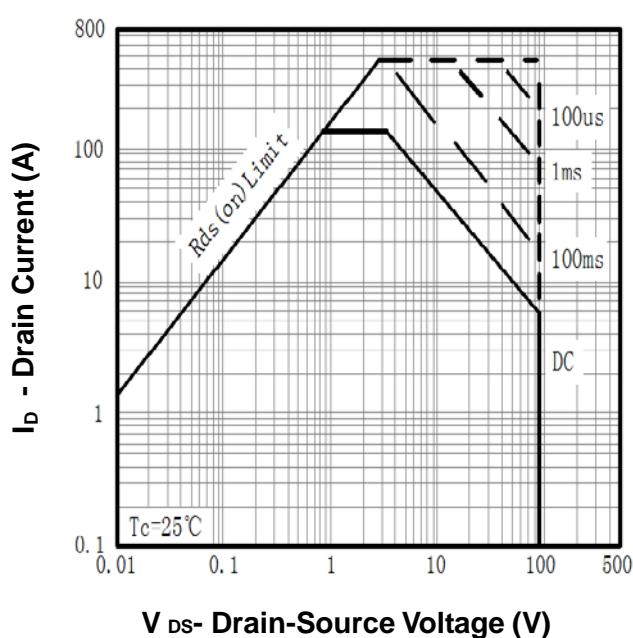
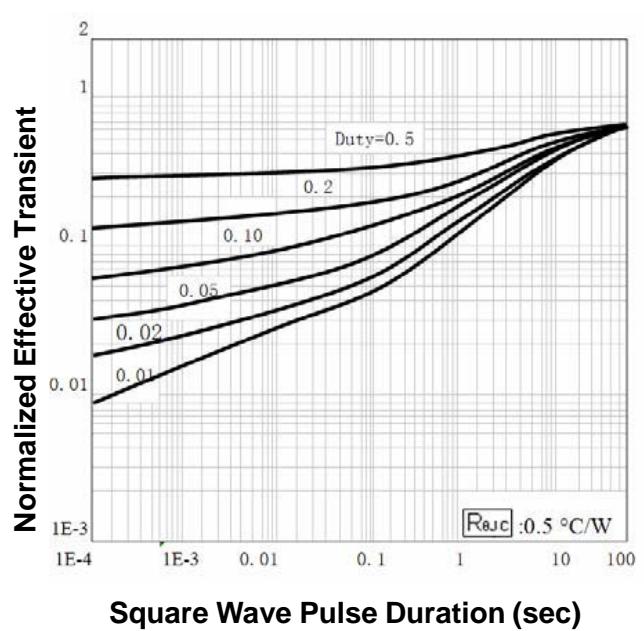
## Source-Drain Diode Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_s$	Continuous Source Diode Forward Current	-	-	120	A	
$I_{sM}$	Pulsed Source Diode Forward Current (Note 1)	-	-	480	A	
$V_{\text{SD}}$	Forward On Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=45\text{A}$	-	0.95	1.4	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=45\text{A}$	-	60	-	ns
	Reverse Recovery Charge		-	56	-	nC

Notes:

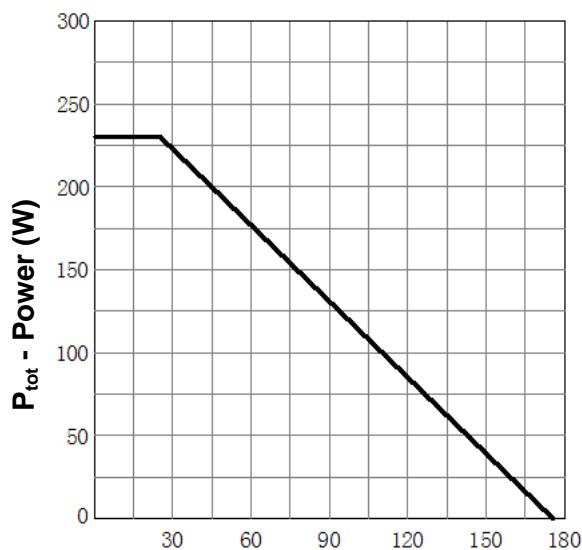
1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L=0.5\text{mH}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $R_G=25\ \Omega$ , Starting  $T_J=25^\circ\text{C}$
3. Pulse Width  $\leq 300\ \mu\text{s}$ ; Duty Cycle  $\leq 2\%$

## Typical Characteristics

**Output Characteristics****Drain Current****Safe Operation Area****Thermal Transient Impedance****V<sub>DS</sub>- Drain-Source Voltage (V)****Square Wave Pulse Duration (sec)**

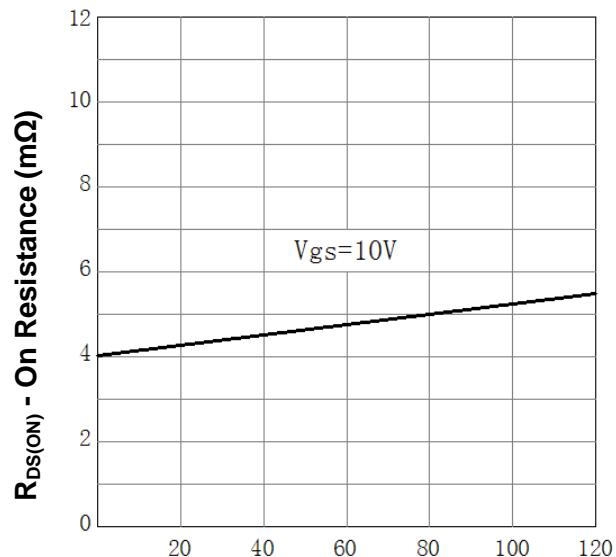
## Typical Characteristics

**Power Dissipation**



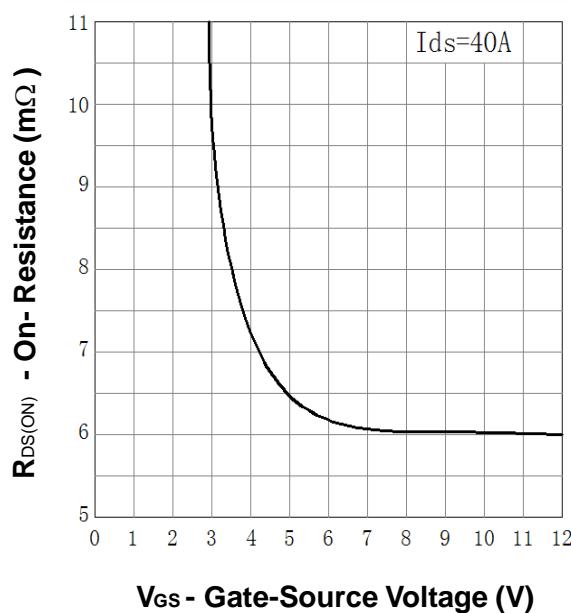
$T_j$  - Junction Temperature (°C)

**Drain-Source On Resistance**



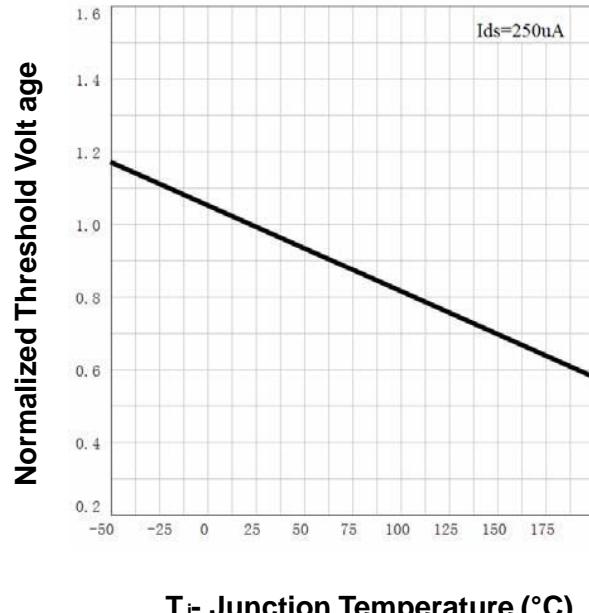
$I_D$ - Drain Current (A)

**Drain-Source On Resistance**



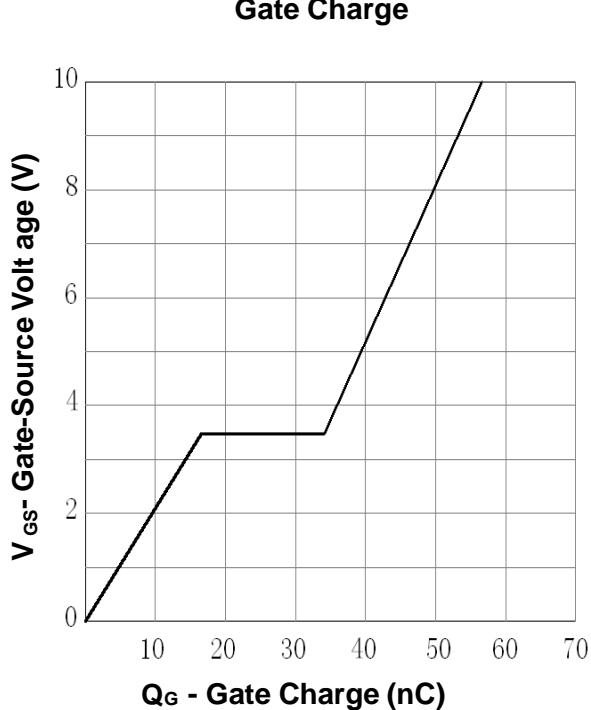
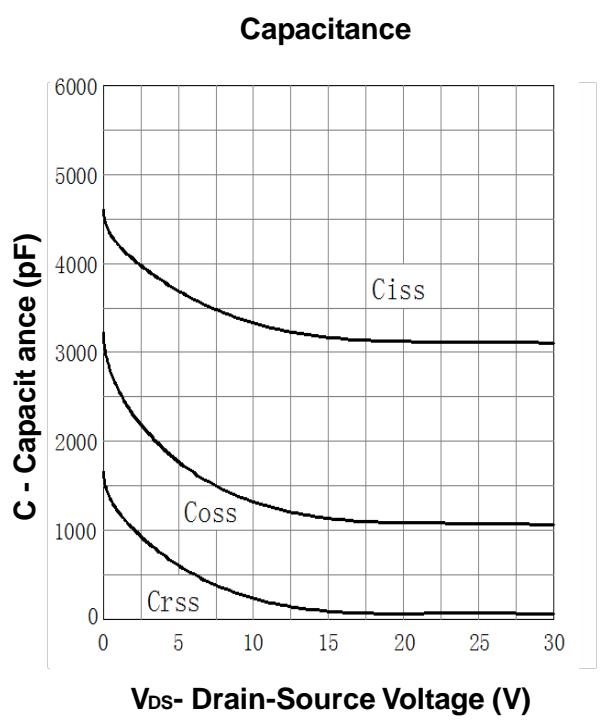
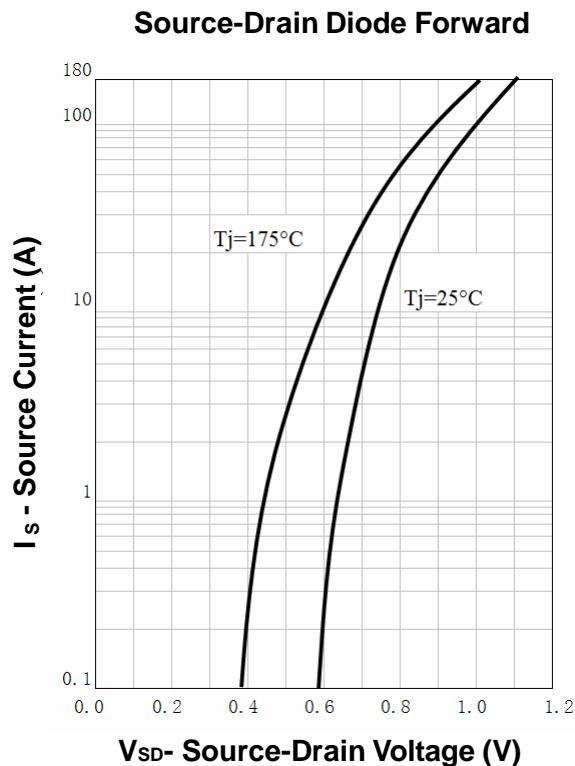
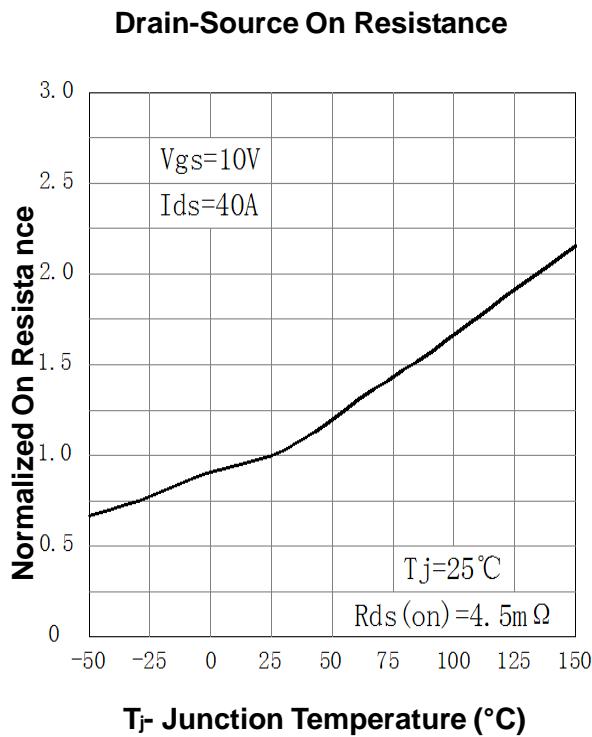
$V_{GS}$  - Gate-Source Voltage (V)

**Gate Threshold Voltage**

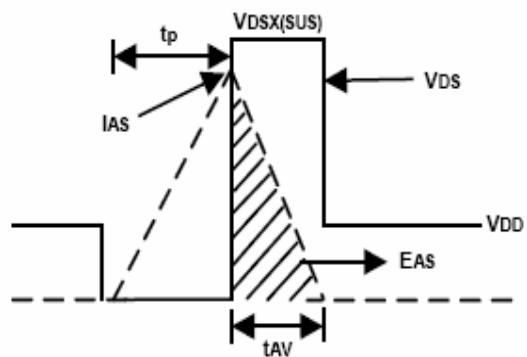
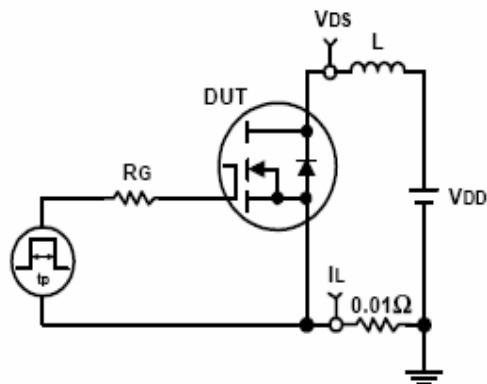


$T_j$ - Junction Temperature (°C)

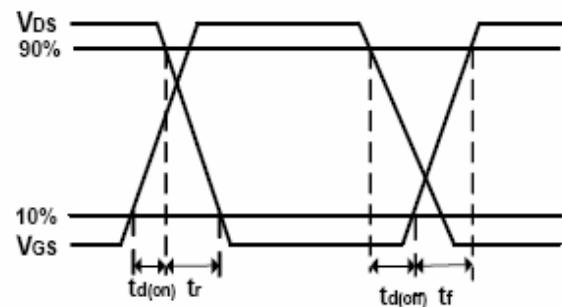
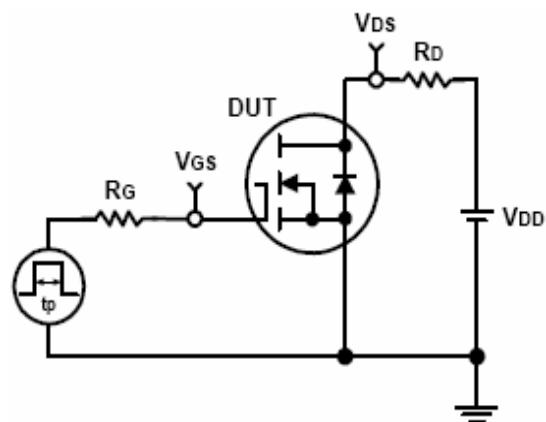
## Typical Characteristics



## Avalanche Test Circuit and Waveforms



## Switching Time Test Circuit and Waveforms



***Si-Tech***

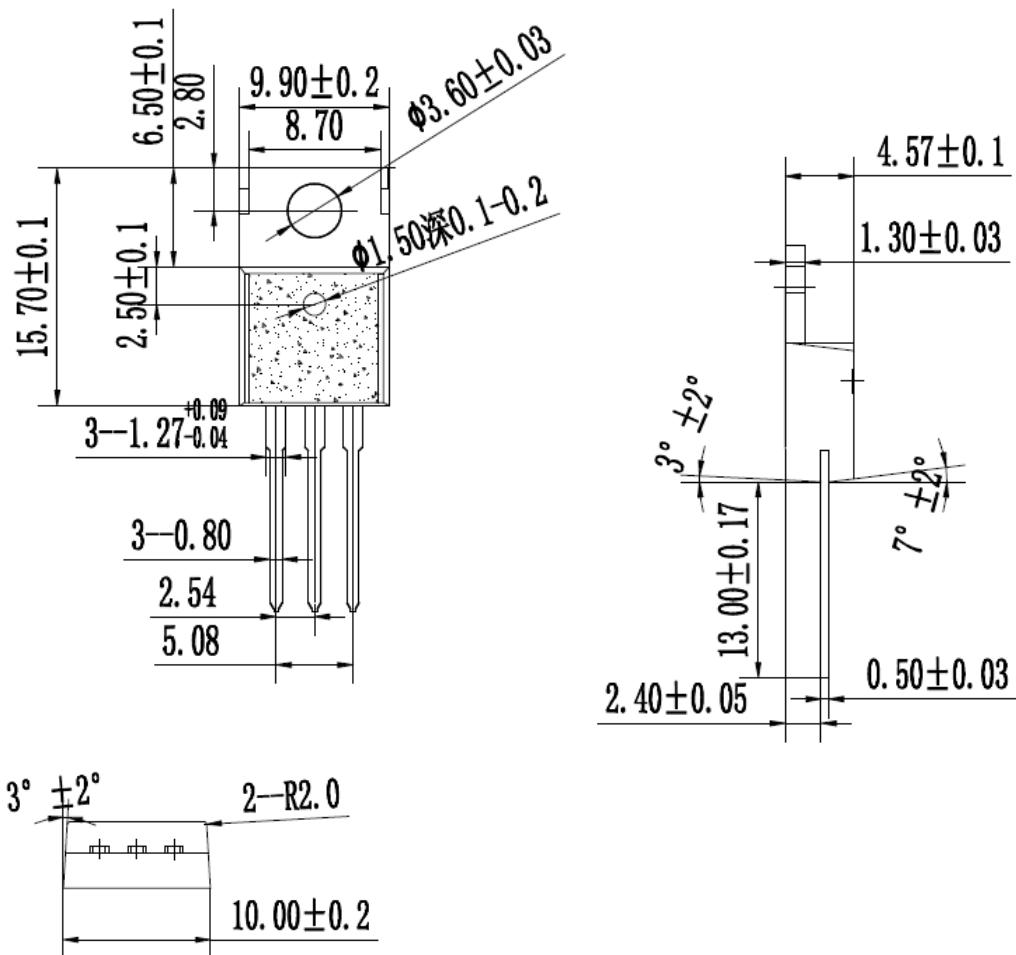
**SI-TECH SEMICONDUCTOR CO.,LTD**

**S90N045R/S**

## Package Outline

Dimensions are shown in millimeters

R: TO220



***Si-Tech***

**SI-TECH SEMICONDUCTOR CO.,LTD**

**S90N045R/S**

**S: TO263 (D<sup>2</sup>PAK)**

